

**TIF™500-30-05U Series** thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effectively enhances the efficiency and life-time of the heat-generating electronic components.

### Features

- » Good thermal conductivity:3.0W/mk
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications

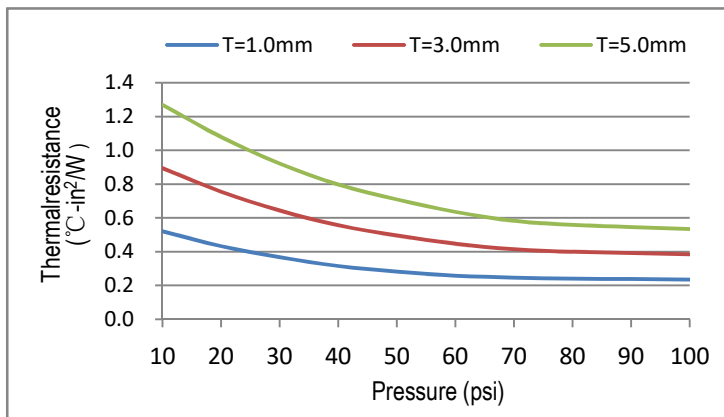
- » Available in varies thickness

### Application

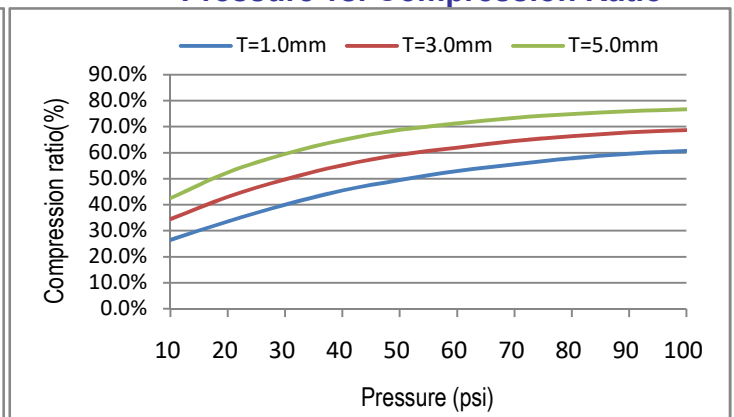
- » Cooling components to the chassis of frame
- » Set Top Box
- » Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

| Typical Properties of TIF™500-30-05U Series |                                   |              |
|---|-----------------------------------|--------------|
| Property                                    | Value                             | Test method  |
| Color                                       | Blue                              | Visual       |
| Construction                                | Ceramic filled silicone elastomer | *****        |
| Thickness range                             | 0.020"(0.5mm)~0.200" (5.0mm)      | ASTM D374    |
| Hardness (Shore 00)                         | 27±5                              | ASTM 2240    |
| Specific Gravity (g/cm <sup>3</sup> )       | 3.0                               | ASTM D792    |
| Operating Temp                              | -40°C~160°C                       | *****        |
| Dielectric Breakdown Voltage (T=1.0mm, Vac) | ≥5500                             | ASTM D149    |
| Dielectric Constant@1MHz                    | 4.5                               | ASTM D150    |
| Volume Resistivity                          | ≥1.0X10 <sup>12</sup> Ohm-cm      | ASTM D257    |
| Thermal Conductivity (W/mK)                 | 3.0                               | ASTM D5470   |
|   | 3.0                               | ISO22007-2.2 |
| Flame Rating                                | 94 -V0                            | UL E331100   |

### Pressure vs. Thermal Impedance



### Pressure vs. Compression Ratio



**Product Thicknesses:** 0.020-inch to 0.200-inch (0.5mm to 5.0mm) **Product Sizes:** 8" x 16"(203mm x406mm)  
 Individual die cut shapes and custom thickness can be supplied. Please contact us for confirming  
 Safe disposal method does not require special protection. The storage condition is low temperature and dry, away from open fire and away from direct sunlight. For detailed method, please refer to the product material safety data sheet.

Thermally Conductive Materials | Thermally Conductive Plastics | Heat Generating Materials | Shielding Materials | Foaming Silica Gel | Die-Cutting Products

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